

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Seok Pyo Song</td> <td>06/26/2008</td> </tr> <tr> <td>Dong Sun Sheen</td> <td>06/26/2008</td> </tr> <tr> <td>Young Jin Lee</td> <td>06/26/2008</td> </tr> <tr> <td>Mi Ri Lee</td> <td>06/26/2008</td> </tr> <tr> <td>Chi Ho Kim</td> <td>06/26/2008</td> </tr> <tr> <td>Gil Jae Park</td> <td>06/26/2008</td> </tr> <tr> <td>Bo Min Seo</td> <td>06/27/2008</td> </tr> </tbody> </table>		Name	Execution Date	Seok Pyo Song	06/26/2008	Dong Sun Sheen	06/26/2008	Young Jin Lee	06/26/2008	Mi Ri Lee	06/26/2008	Chi Ho Kim	06/26/2008	Gil Jae Park	06/26/2008	Bo Min Seo	06/27/2008
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RECEIVING PARTY DATA																	
Name:	Hynix Semiconductor Inc.																
Street Address:	San 136-1, Ami-ri, Bubal-eup																
City:	Icheon-si, Gyeonggi-do																
State/Country:	REPUBLIC OF KOREA																
PROPERTY NUMBERS Total: 1																	
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12164721</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12164721												
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Application Number:	12164721																
CORRESPONDENCE DATA																	
Fax Number:	(312)474-0448																
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>																	
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Correspondent Name:	Marshall, Gerstein & Borun LLP																
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ATTORNEY DOCKET NUMBER:	29925/43940																
NAME OF SUBMITTER:	Sandip H. Patel																

OP \$40.00 12164721

Total Attachments: 2
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MARSHALL, GERSTEIN & BORUN LLP, 233 S. Wacker Drive, Suite 6300, Sears Tower, Chicago, Illinois 60606-6357

ASSIGNMENT

Serial No: 12/164,721

Filed: June 30, 2008

Title: **METHOD OF FABRICATING A NON-VOLATILE MEMORY DEVICE**

For \$10.00 (Ten Dollars) and other good and sufficient consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assign to Hynix Semiconductor Inc., of San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do, Republic of Korea, hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, executed by the undersigned on, June 26, 2008 and in said application and any and all other applications, both United States and foreign, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States and foreign countries, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorize and request the attorneys of record in said application to insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrant themselves to be the owners of the interest herein assigned and to have the right to make this assignment and further warrant that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agree, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, and any and all applications and other documents for Letters Patent in foreign countries on said invention or improvements, that said assignee, its successors or assigns, may deem necessary or expedient, and for the aforesaid consideration the undersigned further agree upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent, both United States and foreign, and vest all rights therein hereby conveyed in said assignee, its successors and assigns,

whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

Date: <u>June 26, 2008</u>	Signature: <u>Seok Pyo Song</u> SONG, Seok Pyo
Date: <u>June 26, 2008</u>	Signature: <u>Dong Sun Sheen</u> SHEEN, Dong Sun
Date: <u>June 26, 2008</u>	Signature: <u>Young Jim Lee</u> LEE, Young Jim
Date: <u>June 26, 2008</u>	Signature: <u>Lee Mi Ri</u> LEE, Mi Ri
Date: <u>June 26, 2008</u>	Signature: <u>Chi Ho Kim</u> KIM, Chi Ho
Date: <u>June 26, 2008</u>	Signature: <u>Park Gil Jae</u> PARK, Gil Jae
Date: <u>June 27, 2008</u>	Signature: <u>Bo Min Seo</u> SEO, Bo Min

